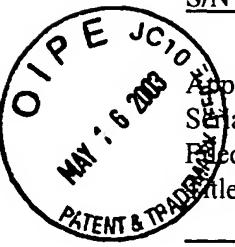


S/N 10/004656

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PATENT
SEARCHED
S/21/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Thomas A. Figura
Serial No.: 10/004656
Filed: December 04, 2001
Title: METHOD AND STRUCTURE FOR IMPROVED ALIGNMENT TOLERANCE IN
MULTIPLE, SINGULARIZED PLUGS



SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. § 1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. § 1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

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Respectfully submitted,

THOMAS A. FIGURA

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
612-373-6969

Date 5-13-03

By Viet V. Tong
Reg. No. 45,416

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, P.O.Box 1450, Alexandria, VA 22313-1450, on this 13 day of May, 2003

Gina M. Lepus

Name

Gina M. Lepus
Signature

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